

- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Super Low Gate Charge
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

RoHS

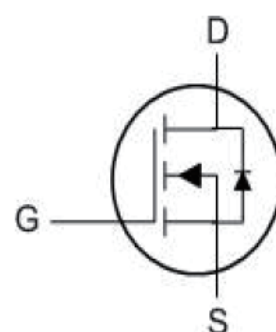
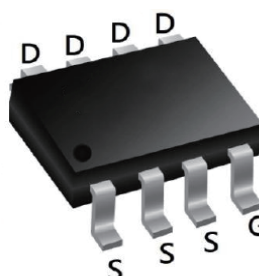
BVDSS	RDS(on)	ID
20V	13mΩ	8A

Description

The 2010S is the high cell density trenched N-ch MOSFETs, which provide excellent $R_{DS(on)}$ and gate charge for most of the synchronous buck converter applications.

The 2010S meet the RoHS and Green Product, requirement 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter		Max.	Units
V_{DS}	Drain-Source Voltage		20	V
V_{GS}	Gate-Source Voltage		± 12	V
I_D	Continuous Drain Current	$T_C = 25^\circ\text{C}$	8	A
I_{DM}	Pulsed Drain Current note1		28	A
P_D	Power Dissipation	$T_C = 25^\circ\text{C}$	2.25	W
T_J, T_{STG}	Operating and Storage Temperature Range		-55 To 150	$^\circ\text{C}$

Thermal Data

Symbol	Parameter	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-ambient ₂	80	$^\circ\text{C/W}$

Electrical Characteristics ($T_J = 25^\circ\text{C}$ unless otherwise specified)

Symbol	Parameter	Test Condition	Min.	Typ.	Max.	Units
Static Characteristics						
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0V, I _D = 250μA	20	-	-	V
I _{GSS}	Gate Leakage Current	V _{GS} = ±12V, V _{DS} = 0V	-	-	±100	nA
I _{DSS}	Drain Cut-off Current	V _{DS} = 20V, V _{GS} = 0V	-	-	1	μA
V _{GS(th)}	Gate Threshold Voltage	V _{GS} = V _{DS} , I _D = 250μA	0.45	0.7	1	V
R _{DS(on)}	Drain-Source On-State Resistance ³	V _{GS} = 4.5V, I _D =5A	-	13	20	mΩ
		V _{GS} = 2.5V, I _D = 4.7A	-	18	30	
		V _{GS} = 1.8V, I _D = 4.3A	-	28	57	
Dynamic Characteristics ⁴						
C _{iss}	Input Capacitance	V _{GS} = 0V, V _{DS} = 10V, f = 1MHz	-	700	-	pF
C _{oss}	Output Capacitance		-	120	-	
C _{rss}	Reverse Transfer Capacitance		-	105	-	
Switching Characteristics ⁴						
Q _g	Total Gate Charge	V _{GS} = 4.5V, V _{DS} = 10V, I _D = 5A	-	10.5	-	nC
Q _{gs}	Gate-Source Charge		-	2	-	
Q _{gd}	Gate-Drain Charge		-	2.5	-	
t _{d(on)}	Turn-On Time	V _{GS} = 5V, V _{DD} = 10V, I _D = 5A,R _G = 3Ω,	-	10	-	ns
t _r	Rise Time		-	20	-	
t _{d(off)}	Turn-Off Time		-	32	-	
t _f	Fall Time		-	12	-	
Source-Drain Diode Characteristics						
V _{SD}	Body Diode Voltage ³	I _S =4A, V _{GS} = 0V	-	-	1.2	V
I _S	Continuous Source Current		-	-	8	A

Notes:

- 1.Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)} = 150^\circ\text{C}$.
- 2.The data tested by surface mounted on a 1 inch² FR-4 board with 20Z copper, The value in any given application depends on the user's specific board design.
- 3.Pulse Test: Pulse width $\leq 300\mu s$, duty cycle $\leq 2\%$.
- 4.This value is guaranteed by design hence it is not included in the production test.

Typical Performance Characteristics

Figure1: Output Characteristics

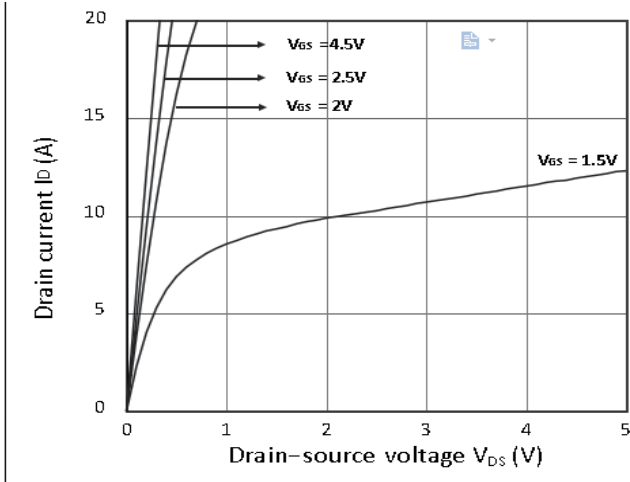


Figure 2: Typical Transfer Characteristics

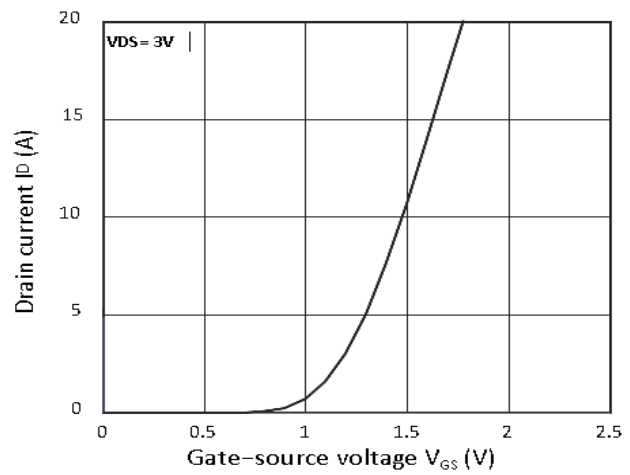


Figure 3: Forward Characteristics of Reverse

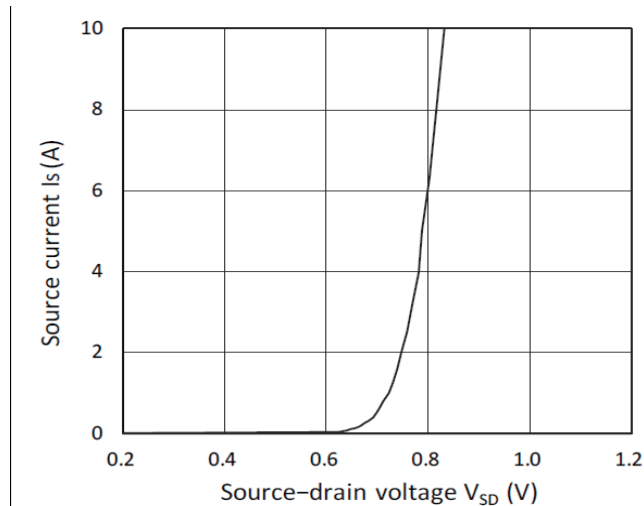


Figure 4: RDS(ON) vs. VGS

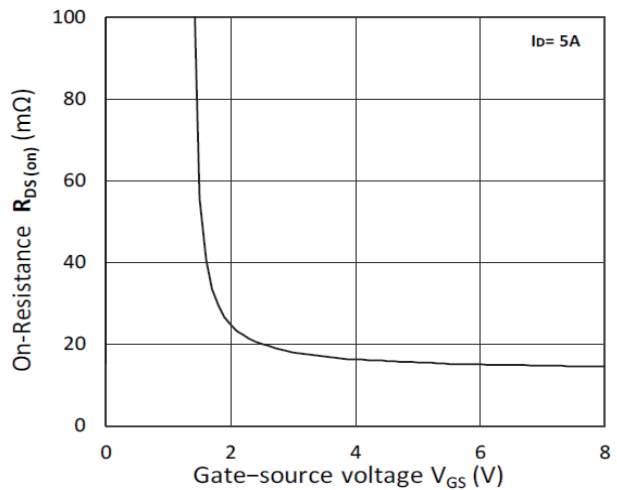


Figure 5: RDS(ON) vs. ID

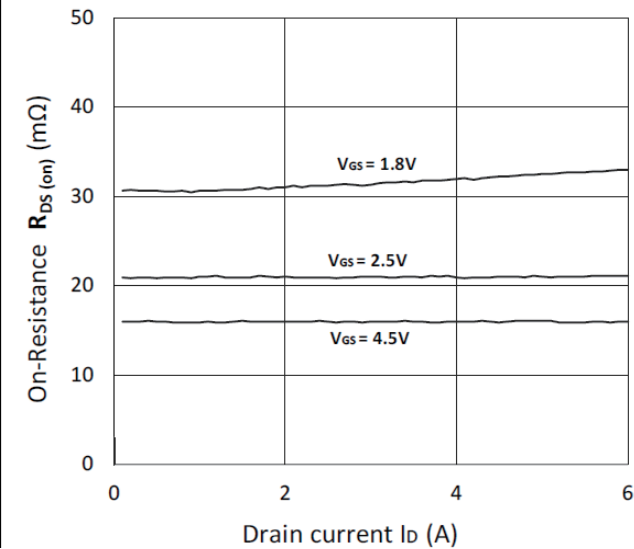
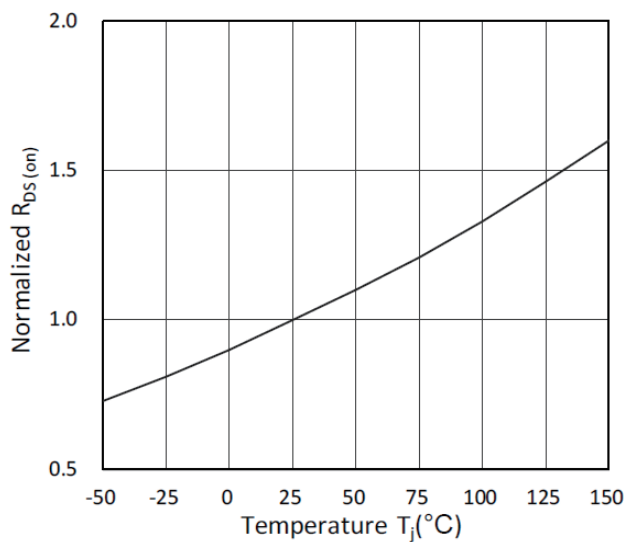


Figure 6: Normalized RDS(on) vs. Temperature



Typical Performance Characteristics

Figure 7: Capacitance Characteristics

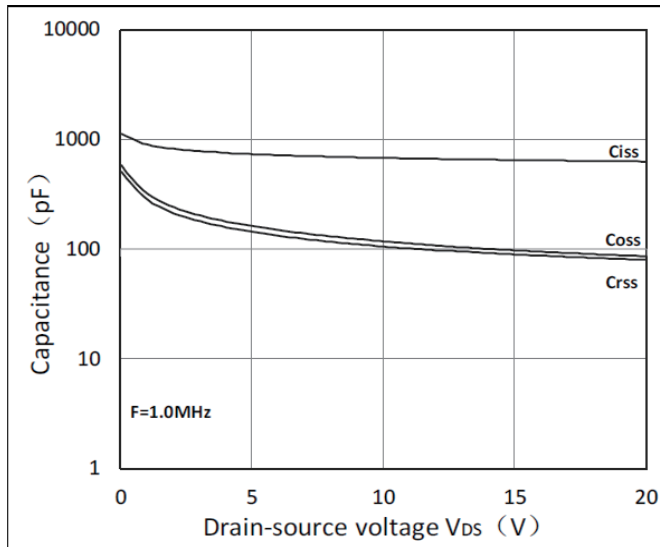
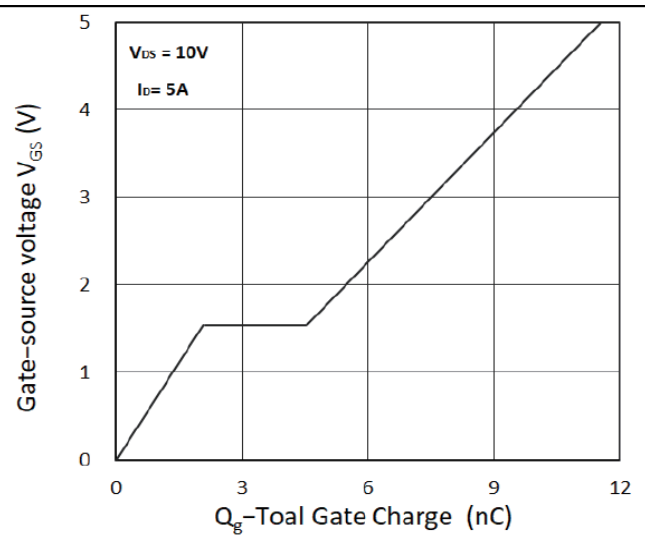
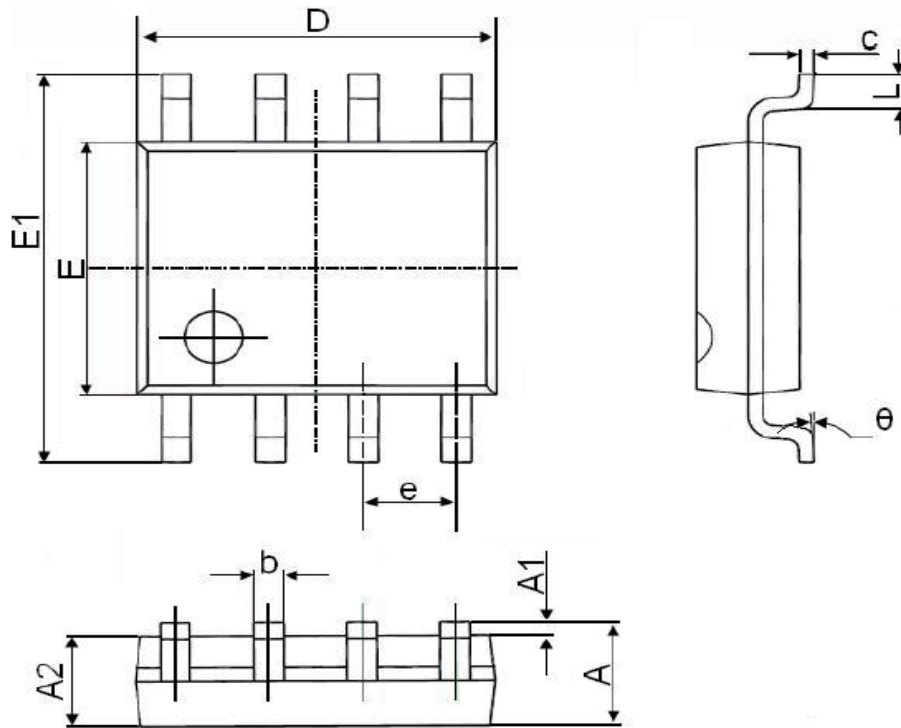


Figure 8: Gate Charge Characteristics



SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°